




# Green Products | 绿色产品

## NP/NPE-free (meet REACH requirement) — 不含壬基酚 (符合欧盟REACH环保规范)

NP (Nonyl Phenol) / NPE (Nonyl Phenol Ethoxylates) are generally used as surfactant. However, due to health and environmental hazards, NP/NPE has been banned in EU.

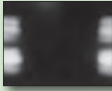
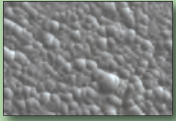
壬基酚一般用作表面活性剂。然而，基于对健康及环境的危害，壬基酚已被欧盟禁止使用。

Product 产品	Features and Benefits 特性及效益	
<b>RONACLEAN™ EVP 200 Cleaner Series</b>	<ul style="list-style-type: none"> <li>One component acid cleaner 单一成份酸性清洁剂</li> <li>Excellent cleaning performance for dry film and other residues 针对乾膜及其它残渣, 具有绝佳的清潔能力</li> <li>Capable of pattern process without damaging dry film 适用于线路镀铜製程, 同时并不会损害乾膜</li> </ul>	 <p>Excellent detergency without damaging dry film 绝佳的清洁能力, 且不损害乾膜</p>
<b>RONASTAN™ EC-1 Tin Plating</b>	<ul style="list-style-type: none"> <li>Matte Tin for etch resist application 雾面锡适用于蚀刻阻剂之应用</li> <li>Best in class throwing power 最佳且均匀的孔内锡层覆盖</li> </ul>	 <p>Excellent coverage and resistance 绝佳的锡层覆盖及抗蚀能力</p>
<b>CRIMSON™ Sensitizer 5123M-1 CIRCUPOSIT™ Conditioner 3323A</b>	<ul style="list-style-type: none"> <li>Excellent and uniform coverage on both glass fiber and resin 在玻璃纤维及树脂上, 皆有绝佳且一致的覆盖性</li> <li>Provide optimum Pd adsorption for all laminate and dielectric materials yielding complete electroless copper coverage 在不同板材上, 提供最优化之钯吸附量, 助于化学沉铜产生完整的覆盖</li> <li>Excellent reliability performance 绝佳的信赖度表现</li> </ul>	 <p>Excellent coverage and reliability performance 绝佳的覆盖性及信赖度表现</p>

## EDTA-free — 不含乙二酸四乙胺

EDTA (Ethylenediaminetetraacetic acid) is a chelating agent. It captures abundant metal ions in solution but itself is not easy to be degraded, making it a persistent organic pollutant.

EDTA作为螯合剂, 它于水溶液中补捉大量金属离子但本身却不易被分解, 使其成为长期有机污染物。

Product 产品	Features and Benefits 特性及效益	
<b>CIRCUPOSIT™ 328 Electroless Copper</b>	<ul style="list-style-type: none"> <li>High-yield, "thin" electroless copper, tartrate-based 高附载, 薄化学沉铜, 酒石酸系统</li> <li>Excellent plating coverage and copper-to-copper bonds achieved with all electroplate coppers 绝佳的化学铜镀层覆盖性, 使其与不同的电镀铜, 皆可达成良好的铜与铜连结力</li> </ul>	 <p>Excellent coverage on PI 在PI上具有绝佳的覆盖能力</p>
<b>AUROELECTROLESS™ SMT 525G Immersion Gold</b>	<ul style="list-style-type: none"> <li>Low gold content operation with 0.5–1.0 g/L 低金含量操作, 金浓度为0.5–1.0 g/L</li> <li>Low gold porosity deposition with very good Ni coverage to avoid corrosion in post treatment process 低疏孔性的化学金层, 良好且緻密地覆盖于镍层之上, 可避免后製程的腐蚀及攻击</li> <li>Compatible with ENEPIG and Selective ENIG process 适用于化学镍钯金及选择性化学镍金製程</li> </ul>	 <p>No Ni corrosion 无镍层腐蚀</p>

## Formaldehyde-free / HCHO-free — 不含甲醛

Formaldehyde is a strong reducing agent. Nonetheless, it causes health damage by inhalation.

甲醛为一强还原剂。不过, 经由吸入会对人体造成健康危害。

Product 产品	Features and Benefits 特性及效益
<b>CRIMSON™ Direct Plating</b>	<ul style="list-style-type: none"> <li>The leading palladium-based direct plate system in horizontal process that creates a stable sulfide conversion coating 硫化钯系统的直接电镀製程, 适用于水平线, 并可产生稳定镀层</li> </ul>
<b>CONDUCTRON™ Direct Plating</b>	<ul style="list-style-type: none"> <li>Unique palladium-based system that creates a conductive direct plate coating with fine quality and high reliability 独特的钯系统直接电镀製程, 可产生良好品质及高信赖度的镀层</li> </ul>



Electronic Materials